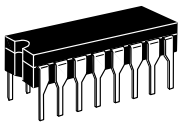
MC14500B

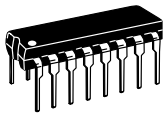
Industrial Control Unit

The MC14500B Industrial Control Unit (ICU) is a single–bit CMOS processor. The ICU is designed for use in systems requiring decisions based on successive single–bit information. An external ROM stores the control program. With a program counter (and output latches and input multiplexers, if required) the ICU in a system forms a stored–program controller that replaces combinatorial logic. Applications include relay logic processing, serial data manipulation and control. The ICU also may control an MPU or be controlled by an MPU.

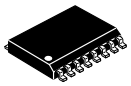
- 16 Instructions
- DC to 1.0 MHz Operation at V_{DD} = 5 V
- On–Chip Clock (Oscillator)
- Executes One Instruction per Clock Cycle
- 3 to 18 V Operation
- Low Quiescent Current Characteristic of CMOS Devices
- Capable of Driving One Low–Power Schottky Load or Two Low–Power TTL Loads over Full Temperature Range



L SUFFIX
CERAMIC
CASE 620



P SUFFIX
PLASTIC
CASE 648



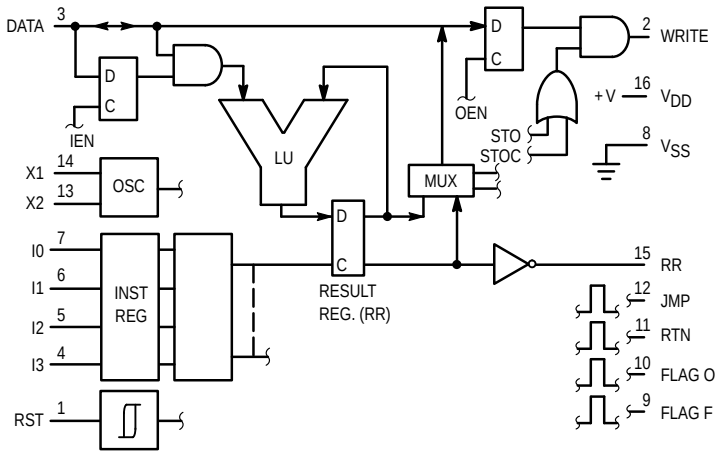
DW SUFFIX
SOIC
CASE 751G

ORDERING INFORMATION

MC14XXXBCP	Plastic
MC14XXXBCL	Ceramic
MC14XXXBDW	SOIC

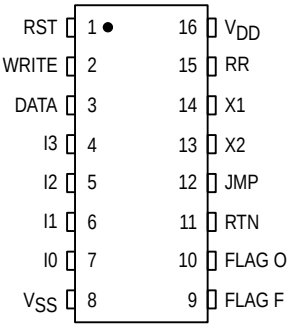
T_A = – 55° to 125°C for all packages.

BLOCK DIAGRAM



X1 — OSCILLATOR OUTPUT
X2 — OSCILLATOR INPUT

PIN ASSIGNMENT



MAXIMUM RATINGS* (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage	– 0.5 to + 18.0	V
V_{in}, V_{out}	Input or Output Voltage (DC or Transient)	– 0.5 to V_{DD} + 0.5	V
I_{in}, Iout	Input or Output Current (DC or Transient), per Pin	± 10	mA
P_D	Power Dissipation, per Package†	500	mW
T_{stg}	Storage Temperature	– 65 to + 150	°C
T_L	Lead Temperature (8–Second Soldering)	260	°C

* Maximum Ratings are those values beyond which damage to the device may occur.
†Temperature Derating:
Plastic “P and D/DW” Packages: – 7.0 mW/°C From 65°C To 125°C
Ceramic “L” Packages: – 12 mW/°C From 100°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \le (V_{in}$ or $V_{out}) \le V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	– 55°C Min	– 55°C Max	25°C Min	25°C Typ #	25°C Max	125°C Min	125°C Max	Unit
Output Voltage “0” Level	V_{OL}	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
V_{in} = V_{DD} or 0		10	—	0.05	—	0	0.05	—	0.05	
		15	—	0.05	—	0	0.05	—	0.05	
“1” Level	V_{OH}	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
V_{in} = 0 or V_{DD}		10	9.95	—	9.95	10	—	9.95	—	
		15	14.95	—	14.95	15	—	14.95	—	
Input Voltage “0” Level	V_{IL}									Vdc
RST, D, X2										
(V_O = 4.5 or 0.5 Vdc)		5.0	—	1.5	—	2.25	1.5	—	1.5	
(V_O = 9.0 or 1.0 Vdc)		10	—	3.0	—	4.50	3.0	—	3.0	
(V_O = 13.5 or 1.5 Vdc)		15	—	4.0	—	6.75	4.0	—	4.0	
“1” Level	V_{IH}									Vdc
(V_O = 0.5 or 4.5 Vdc)		5.0	3.5	—	3.5	2.75	—	3.5	—	
(V_O = 1.0 or 9.0 Vdc)		10	7.0	—	7.0	5.50	—	7.0	—	
(V_O = 1.5 or 13.5 Vdc)		15	11	—	11	8.25	—	11	—	
Input Voltage # “0” Level	V_{IL}									Vdc
I0, I1, I2, I3										
(V_O = 4.5 or 0.5 Vdc)		5.0	—	0.8	—	1.1	0.8	—	0.8	
(V_O = 9.0 or 1.0 Vdc)		10	—	1.6	—	2.2	1.6	—	1.6	
(V_O = 13.5 or 1.5 Vdc)		15	—	2.4	—	3.4	2.4	—	2.4	
“1” Level	V_{IH}									Vdc
(V_O = 0.5 or 4.5 Vdc)		5.0	2.0	—	2.0	1.9	—	2.0	—	
(V_O = 1.0 or 9.0 Vdc)		10	6.0	—	6.0	3.1	—	6.0	—	
(V_O = 1.5 or 13.5 Vdc)		15	10	—	10	4.3	—	10	—	
Output Drive Current Source	I_{OH}									mAdc
Data, Write										
(V_{OH} = 4.6 Vdc)		5.0	– 1.2	—	– 1.0	– 2.0	—	– 0.7	—	
(V_{OH} = 9.5 Vdc)		10	– 3.6	—	– 3.0	– 6.0	—	– 2.1	—	
(V_{OH} = 13.5 Vdc)		15	– 7.2	—	– 6.0	– 12	—	– 4.2	—	
(V_{OL} = 0.4 Vdc) Sink	I_{OL}	5.0	1.9	—	1.6	3.2	—	1.1	—	mAdc
(V_{OL} = 0.5 Vdc)		10	3.6	—	3.0	6.0	—	2.1	—	
(V_{OL} = 1.5 Vdc)		15	7.2	—	6.0	12	—	4.2	—	
Output Drive Current Source	I_{OH}									mAdc
Other Outputs										
(V_{OH} = 2.5 Vdc)		5.0	– 3.0	—	– 2.4	– 4.2	—	– 1.7	—	
(V_{OH} = 4.6 Vdc)		5.0	– 0.64	—	– 0.51	– 0.88	—	– 0.36	—	
(V_{OH} = 9.5 Vdc)		10	– 1.6	—	– 1.3	– 2.25	—	– 0.9	—	
(V_{OH} = 13.5 Vdc)		15	– 4.2	—	– 3.4	– 8.8	—	– 2.4	—	
(V_{OL} = 0.4 Vdc) Sink	I_{OL}	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
(V_{OL} = 0.5 Vdc)		10	1.6	—	1.3	2.25	—	0.9	—	
(V_{OL} = 1.5 Vdc)		15	4.2	—	3.4	8.8	—	2.4	—	

#Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

ELECTRICAL CHARACTERISTICS — continued (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	–55°C		25°C			125°C		Unit
			Min	Max	Min	Typ #	Max	Min	Max	
Input Current, RST	I_{in}	15	25	—	—	150	—	—	250	µAdc
Input Current	I_{in}	15	—	± 0.1	—	±0.00001	± 0.1	—	± 1.0	µAdc
Input Capacitance (Data)	C_{in}	—	—	—	—	15	—	—	—	pF
Input Capacitance (All Other Inputs)	C_{in}	—	—	—	—	5.0	7.5	—	—	pF
Quiescent Current (Per Package) I_{out} = 0 µA, V_{in} = 0 or V_{DD}	I_{DD}	5.0 10 15	— — —	5.0 10 20	— — —	0.005 0.010 0.015	5.0 10 20	— — —	150 300 600	µAdc
**Total Supply Current at an External Load Capacitance (C_L) on All Outputs	I_T	—	I_T = (1.5 µA/kHz) f + I_{DD} I_T = (3.0 µA/kHz) f + I_{DD} I_T = (4.5 µA/kHz) f + I_{DD}							µAdc

** The formulas given are for the typical characteristics only at 25°C.
#Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

SWITCHING CHARACTERISTICS* (T_A = 25°C; t_r = t_f = 20 ns for X and I inputs; C_L = 50 pF for JMP, X1, RR, Flag O, Flag F; C_L = 130 pF + 1 TTL load for Data and Write.)

Characteristic	Symbol	V_{DD} Vdc	All Types			Unit
			Min	Typ #	Max	
Propagation Delay Time, X1 to RR	t_{PLH}, t_{PHL}	5.0 10 15	— — —	250 125 100	500 250 200	ns
X1 to Flag F, Flag O, RTN, JMP		5.0 10 15	— — —	200 100 85	400 200 170	
X1 to Write		5.0 10 15	— — —	225 125 100	450 250 200	
X1 to Data		5.0 10 15	— — —	250 120 100	500 240 200	
RST to RR		5.0 10 15	— — —	250 125 100	500 250 200	
RST to X1		5.0 10 15	— — —	450 200 150	Note 1	
RST to Flag F, Flag O, RTN, JMP		5.0 10 15	— — —	400 200 150	800 400 300	
RST to Write, Data		5.0 10 15	— — —	450 225 175	900 450 350	
Clock Pulse Width, X1	$t_{W(cl)}$	5.0 10 15	400 200 180	200 100 90	— — —	ns
Rent Pulse Width, RST	$t_{W(R)}$	5.0 10 15	500 250 200	250 125 100	— — —	ns
Setup Time — Instruction	$t_{su(I)}$	5.0 10 15	400 250 180	200 125 90	— — —	ns
Data	$t_{su(D)}$	5.0 10 15	200 100 80	100 50 40	— — —	
Hold Time — Instruction	$t_{h(I)}$	5.0 10 15	100 50 50	0 0 0	— — —	ns
Data	$t_{h(D)}$	5.0 10 15	200 100 100	100 50 50	— — —	

NOTE 1. Maximum Reset Delay may extend to one–half clock period.
#Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

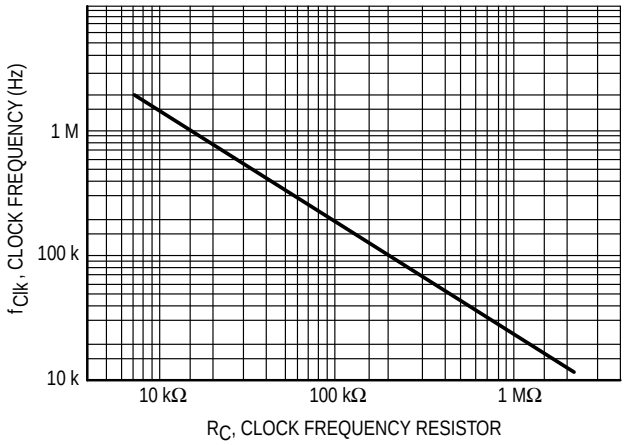


Figure 1. Typical Clock Frequency versus Resistor (R_C)

Pin No.	Function	Symbols
1	Chip Reset	RST
2	Write Pulse	Write
3	Data In/Out	Data
4	MSB Instruction Word	I_3
5	Bit 2 Instruction Word	I_2
6	Bit 1 Instruction Word	I_1
7	LSB Instruction Word	I_0
8	Negative Supply (Ground)	V_{SS}
9	Flag on NOP F	Flag F
10	Flag on NOP O	Flag O
11	Subroutine Return Flag	RTN
12	Jump Instruction Flag	JMP
13	Oscillator Input	X2
14	Oscillator Output	X1
15	Result Register	RR
16	Positive Supply	V_{DD}

Table 1. MC14500B Instruction Set

Instruction Code		Mnemonic	Action
0	0000	NOPO	No change in registers. RR → RR, Flag O → ⎍
1	0001	LD	Load result register. Data → RR
2	0010	LDC	Load complement. $\overline{\text{Data}}$ → RR
3	0011	AND	Logical AND. RR • Data → RR
4	0100	ANDC	Logical AND complement. RR • $\overline{\text{Data}}$ → RR
5	0101	OR	Logical OR. RR + Data → RR
6	0110	ORC	Logical OR complement. RR + $\overline{\text{Data}}$ → RR
7	0111	XNOR	Exclusive NOR. If RR = Data, RR → 1
8	1000	STO	Store. RR → Data Pin, Write → ⎍
9	1001	STOC	Store complement. $\overline{\text{RR}}$ → Data Pin, Write → ⎍
A	1010	IEN	Input enable. Data → IEN Register
B	1011	OEN	Output enable. Data → OEN Register
C	1100	JMP	Jump. JMP Flag → ⎍
D	1101	RTN	Return. RTN Flag → ⎍ and skip next instruction
E	1110	SKZ	Skip next instruction if RR = 0
F	1111	NOPF	No change in registers. RR → RR, Flag F → ⎍

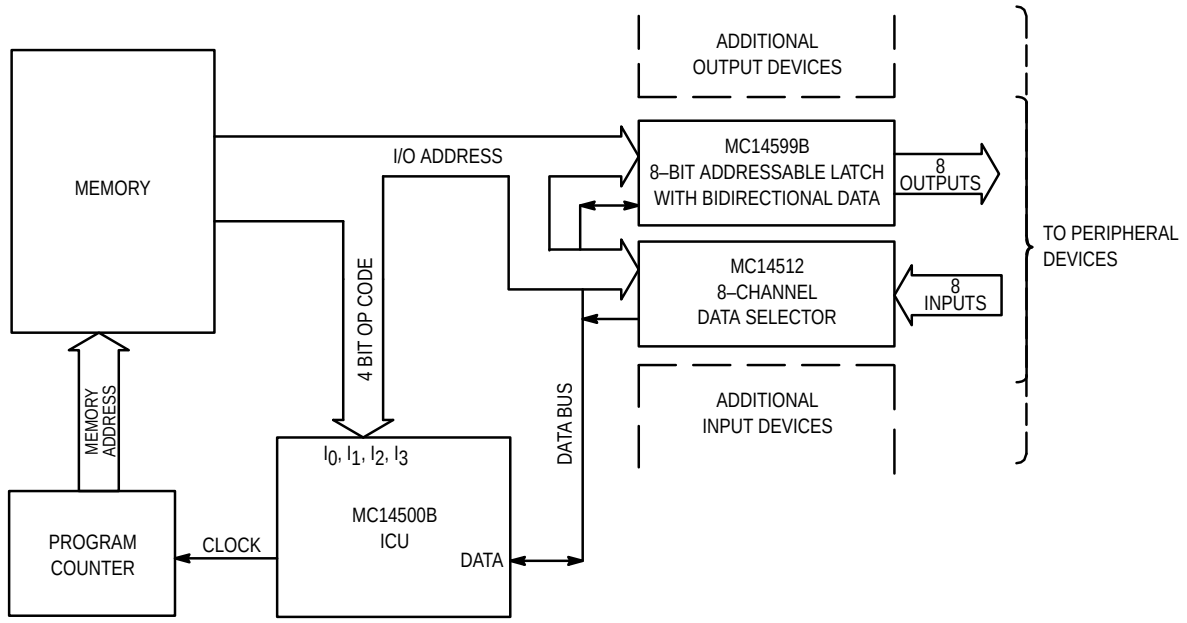
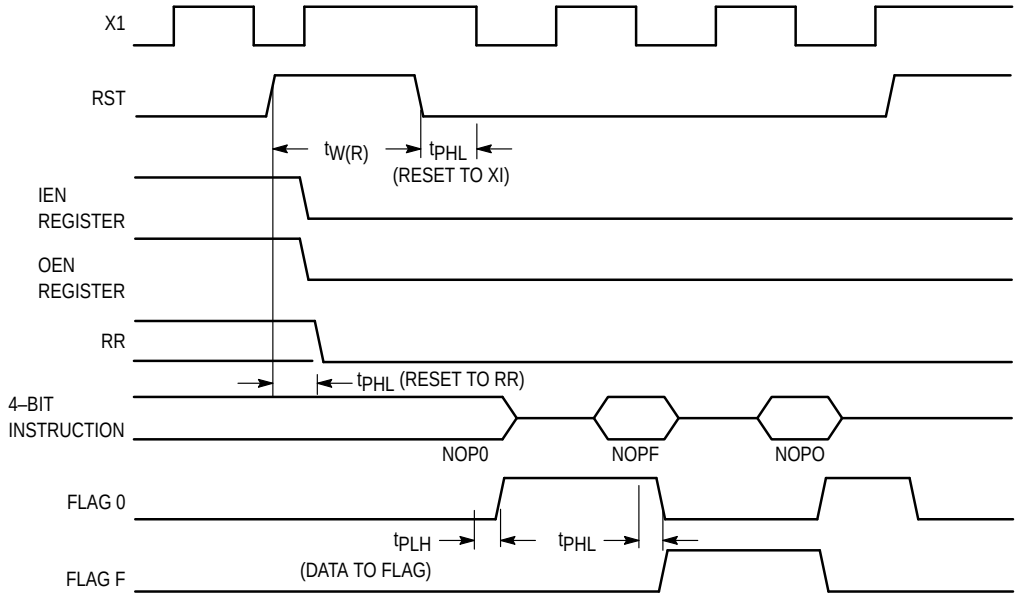


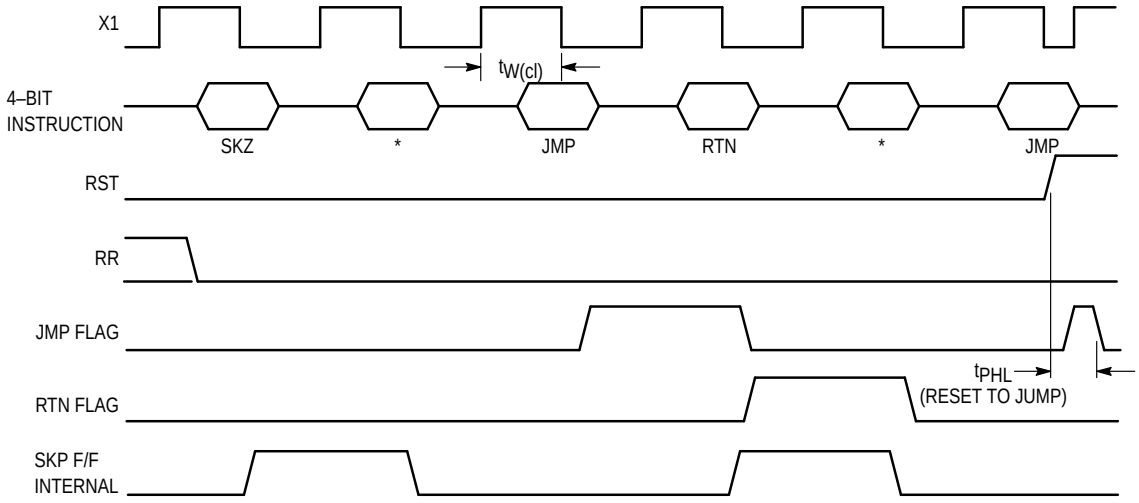
Figure 2. Outline of a Typical Organization for a MC14500B–Based System

TIMING WAVEFORMS

Instructions NOPO, NOPF
RR, IEN, OEN remain unaffected



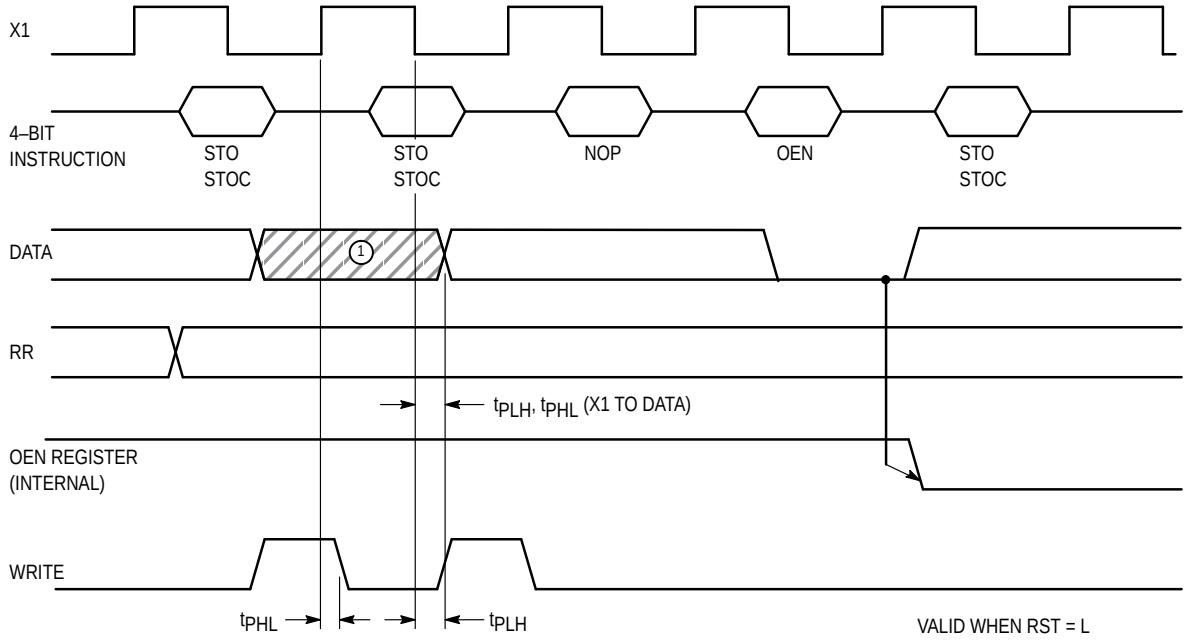
Instructions SKZ, JMP, RTN
RR, IEN, OEN remain unaffected



* Instructions Ignored.

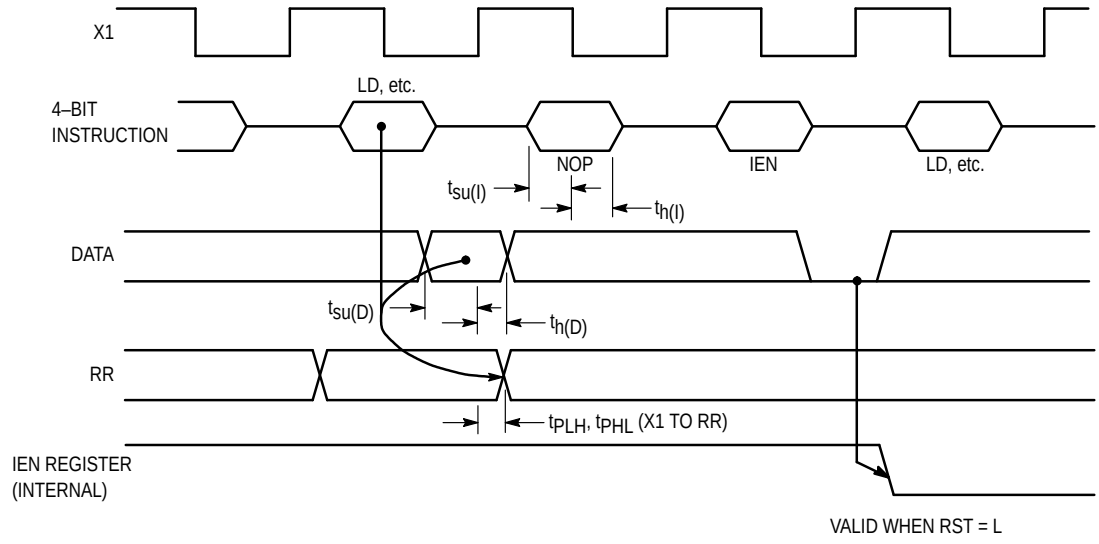
TIMING WAVEFORMS

Instructions STO, STOC, OEN



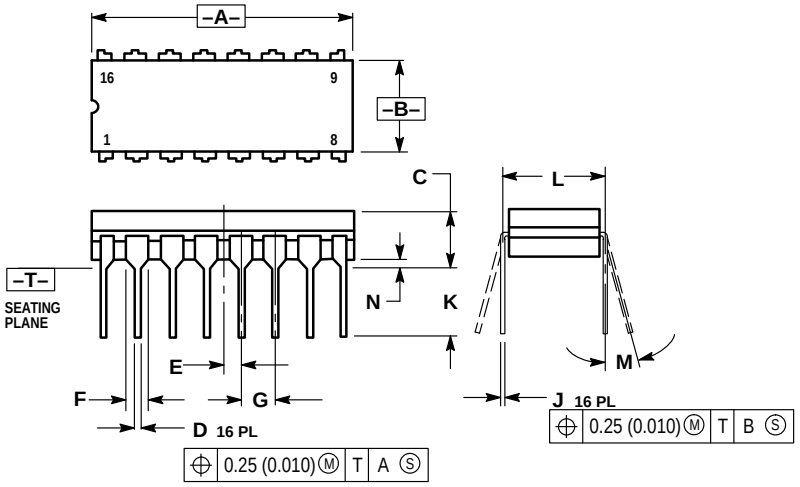
NOTE 1. Valid output data.

Instructions LD, LDC, AND, ANDC OR, ORC, XNOR, IEN



OUTLINE DIMENSIONS

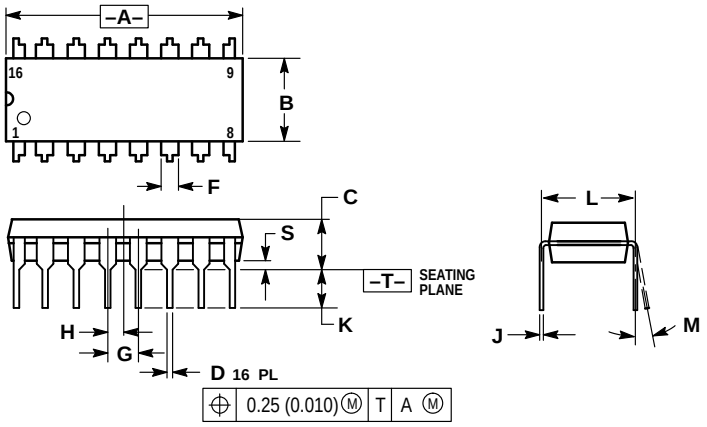
L SUFFIX
CERAMIC DIP PACKAGE
CASE 620–10
ISSUE V



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.020	0.040	0.51	1.01

P SUFFIX
PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R

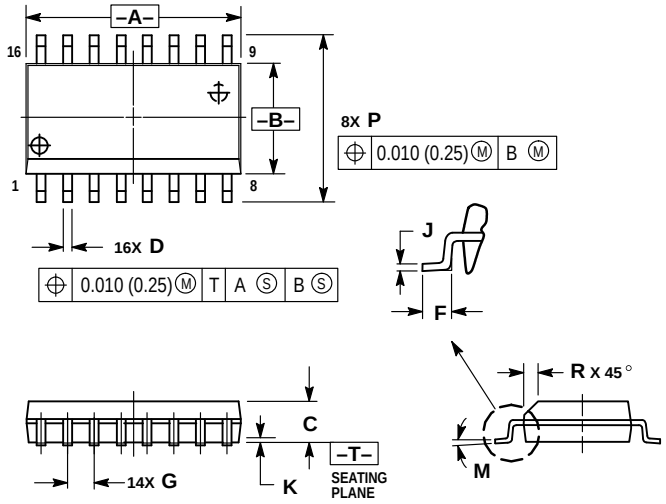


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

OUTLINE DIMENSIONS

DW SUFFIX
PLASTIC SOIC PACKAGE
CASE 751G–02
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

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